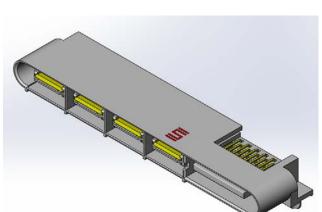
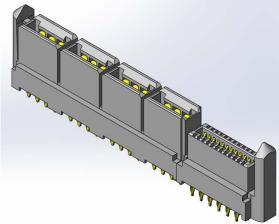


Project Number: Design Qualification Test Report	Tracking Code: 264949_Report_Rev_1
Requested by: Leo Lee	Date: 9/28/2014
Part #: LPHT-08-32-S-RT1-GP/Molex vertical socket: 46114-8320	
Part description: LPHT/ Molex socket	Tech: Kason He
Test Start: 6/29/2013	Test Completed: 8/21/2013









# DESIGN QUALIFICATION TEST REPORT

LPHT/Molex socket LPHT-08-32-S-RT1-GP/Molex vertical socket: 46114-8320

Tracking Code: 264949_Report_Rev_1	Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320
Part description: I	PHT/ Moley socket

# **REVISION HISTORY**

DATA	REV.NUM.	DESCRIPTION	ENG
9/28/2014	1	Initial Issue	КН

#### **CERTIFICATION**

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to ISO 10012-1 and ANSI/NCSL 2540-1, as applicable.

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#### **SCOPE**

To perform the following tests: Design Qualification test. Please see test plan.

## APPLICABLE DOCUMENTS

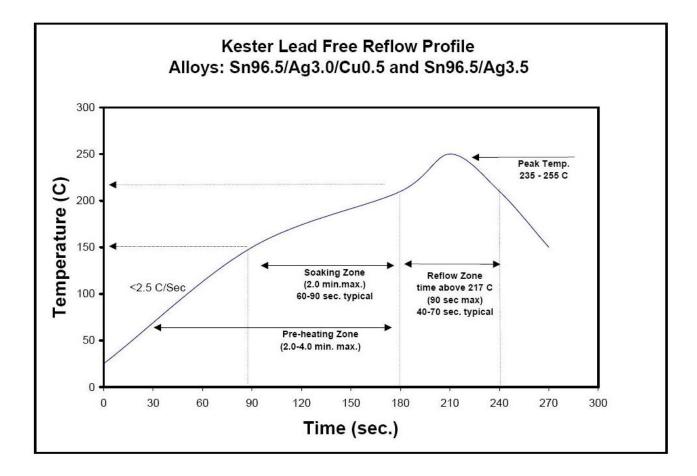
Standards: EIA Publication 364

### TEST SAMPLES AND PREPARATION

- 1) All materials were manufactured in accordance with the applicable product specification.
- 2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
- 3) After soldering, the parts to be used for LLCR testing were cleaned according to TLWI-0001.
- 4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
- 5) The automated procedure is used with aqueous compatible soldering materials.
- 6) Parts not intended for testing LLCR are visually inspected and cleaned if necessary.
- 7) Any additional preparation will be noted in the individual test sequences.
- 8) Solder Information: Lead Free
- 9) Re-Flow Time/Temp: See accompanying profile.
- 10) Samtec Test PCBs used: PCB-104068-TST/PCB-104067-TST

## **TYPICAL OVEN PROFILE (Soldering Parts to Test Boards)**

Tracking Code: 264949\_Report\_Rev\_1



Tracking Code: 264949\_Report\_Rev\_1

Part description: LPHT/ Molex socket

#### **FLOWCHARTS**

## **Durability/Mating/Unmating/Gaps**

TEST	GROUP B1
1231	8 Boards
STEP	(largest position submitted),
0.2.	.0335"/.0422" ENIG PTH
01	Contact Gaps
02	LLCR-1
03	Forces - Mating / Unmating
04	25 Cycles
05	Forces - Mating / Unmating
06	25 Cycles (50 Total)
07	Forces - Mating / Unmating
08	25 Cycles (75 Total)
09	Forces - Mating / Unmating
10	25 Cycles (100 Total)
11	Forces - Mating / Unmating
12	Clean w/Compressed Air
13	Contact Gaps
14	LLCR-2
15	Thermal Shock
13	(Mated and Undisturbed)
16	LLCR-3
17	Cyclic Humidity
''	(Mated and Undisturbed)
18	LLCR-4
19	Forces - Mating / Unmating

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

Mating / Unmating Forces = EIA-364-13

Contact Gaps / Height - No standard method. Usually measured optically.

Gaps to be taken on a minimum of 20% of each part tested

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

Tracking Code: 264949\_Report\_Rev\_1 Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320

Part description: LPHT/ Molex socket

## **FLOWCHARTS Continued**

## **Current Carrying Capacity - Power Pins**

TEST	GROUP A1	GROUP A2	GROUP A3	GROUP A4	
STEP	3 Mated Assemblies 3 Mated Assemblies		3 Mated Assemblies	3 Mated Assemblies	
	2 Contact Powered .0335"/.0422" ENIG PTH	4 Contacts Powered .0335"/.0422" ENIG PTH	6 Contacts Powered .0335"/.0422" ENIG PTH	All Contacts Powered .0335"/.0422" ENIG PTH	
	• • • • •				

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C after derating 20% and based on 105°C (GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C after derating 20% and based on 125°C CCC, Temp rise = EIA-364-70

Tracking Code: 264949 Report Rev 1 Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320

Part description: LPHT/ Molex socket

#### ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

#### THERMAL SHOCK:

- 1) EIA-364-32, Thermal Shock (Temperature Cycling) Test Procedure for Electrical Connectors.
- 2) Test Condition 1: -55°C to +85°C
- 3) Test Time: ½ hour dwell at each temperature extreme
- 4) Number of Cycles: 100
- 5) All test samples are pre-conditioned at ambient.
- 6) All test samples are exposed to environmental stressing in the mated condition.

#### **HUMIDITY:**

- 1) Reference document: EIA-364-31, Humidity Test Procedure for Electrical Connectors.
- 2) Test Condition B, 240 Hours.
- 3) Method III, +25° C to +65° C, 90% to 98% Relative Humidity excluding sub-cycles 7a and 7b.
- 4) All samples are pre-conditioned at ambient.
- 5) All test samples are exposed to environmental stressing in the mated condition.

#### **MATING/UNMATING:**

- 1) Reference document: EIA-364-13, Mating and Unmating Forces Test Procedure for Electrical Connectors.
- 2) The full insertion position was to within 0.003" to 0.004" of the plug bottoming out in the receptacle to prevent damage to the system under test.
- 3) One of the mating parts is secured to a floating X-Y table to prevent damage during cycling.

## **TEMPERATURE RISE (Current Carrying Capacity, CCC):**

- 1) EIA-364-70, Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets.
- 2) When current passes through a contact, the temperature of the contact increases as a result of  $I^2R$  (resistive) heating.
- 3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
- 4) The size of the temperature probe can affect the measured temperature.
- 5) Copper traces on PC boards will contribute to temperature rise:
  - a. Self heating (resistive)
  - b. Reduction in heat sink capacity affecting the heated contacts
- 6) A de-rating curve, usually 20%, is calculated.
- 7) Calculated de-rated currents at three temperature points are reported:
  - a. Ambient
  - b.  $65^{\circ}$  C
  - c.  $75^{\circ}$  C
  - d. 95° C
- 8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
- 9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
- 10) A computer program, TR 803.exe, ensures accurate stability for data acquisition.
- 11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
- 12) Hook-up wire length is longer than the minimum specified in the referencing standard.

Tracking Code: 264949\_Report\_Rev\_1 Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320
Part description: LPHT/ Molex socket

## **ATTRIBUTE DEFINITIONS Continued**

The following is a brief, simplified description of attributes.

#### LLCR:

- 1) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 2) A computer program, LLCR 221.exe, ensures repeatability for data acquisition.
- 3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
  - a. <= +5.0 mOhms: ------ Stable b. +5.1 to +10.0 mOhms: ---- Minor c. +10.1 to +15.0 mOhms: ---- Acceptable d. +15.1 to +50.0 mOhms: ---- Marginal e. +50.1 to +2000 mOhms: ---- Unstable f. >+2000 mOhms: ---- Open Failure

Part description: LPHT/ Molex socket

#### **RESULTS**

## Temperature Rise, CCC at a 20% de-rating

Tracking Code: 264949 Report Rev 1

- CCC for a 30°C Temperature Rise-----29.1 A per contact with 2 contacts (2x1) powered
- CCC for a 30°C Temperature Rise-----26.1 A per contact with 4 contacts (2x2) powered
- CCC for a 30°C Temperature Rise-----22.4 A per contact with 6 contacts (2x3) powered
- CCC for a 30°C Temperature Rise-----21.9 A per contact with 8 contacts (2x4) powered

#### **Mating – Unmating Forces**

- Initial
  - Mating
    - Min -----10.02 Lbs
    - Max-----10.82 Lbs
  - Unmating
    - Min -----7.18 Lbs
    - Max------ 8.52 Lbs
- After 25 Cycles
  - o Mating
    - Min ------10.53 Lbs
    - Max-----11.27 Lbs
  - o Unmating
    - Min ------ 8.46 Lbs
    - Max-----9.54 Lbs
- After 50 Cycles
  - Mating
    - Min ------10.90 Lbs
    - Max-----11.67 Lbs
  - Unmating
    - Min ----- 8.59 Lbs
    - Max-----10.11 Lbs
- After 75 Cycles
  - Mating
    - Min ------11.11 Lbs
      - Max-----11.98 Lbs
  - Unmating
    - Min ----- 8.93 Lbs
    - Max-----10.56 Lbs
- After 100 Cycles
  - Mating
    - Min ------11.32 Lbs
    - Max-----12.16 Lbs
  - o Unmating
    - Min ----- 9.30 Lbs
    - Max-----10.88 Lbs
- Humidity
  - Mating
    - Min ------ 8.13 Lbs
    - Max----- 9.66 Lbs
  - Unmating
    - Min ----- 6.00 Lbs
    - Max-----7.33 Lbs

## **RESULTS Continued**

	RE	SULTS Continued	
	ing/Unmating Durability Group	o (192 LLCR test points)	
nal pin	ıl	22.92 Oh More	
		22.83 mOnms Wax	
	bility,100 Cycles	160 Dointe	C4ahla
C			
С			
C			
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C		Points	Open Fam
	mal Shock	160 Deleate	64-1-1-
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	bility, 100 Cycles	22.7.1	G. 11
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C			
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C		0 Points	Open Failt
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C			
C			
C			
С			O .
_	+50.1 to +2000 mOhms	0 Points	Unstable
C	>+2000 mOhms		

Tracking Code: 264949\_Report\_Rev\_1 Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320

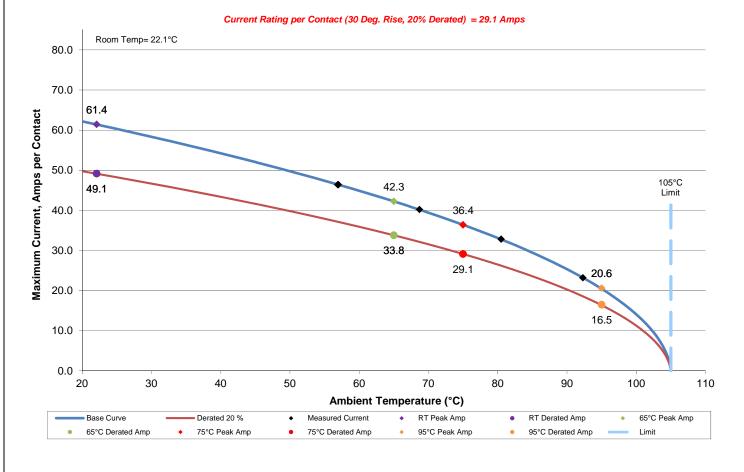
Part description: LPHT/ Molex socket

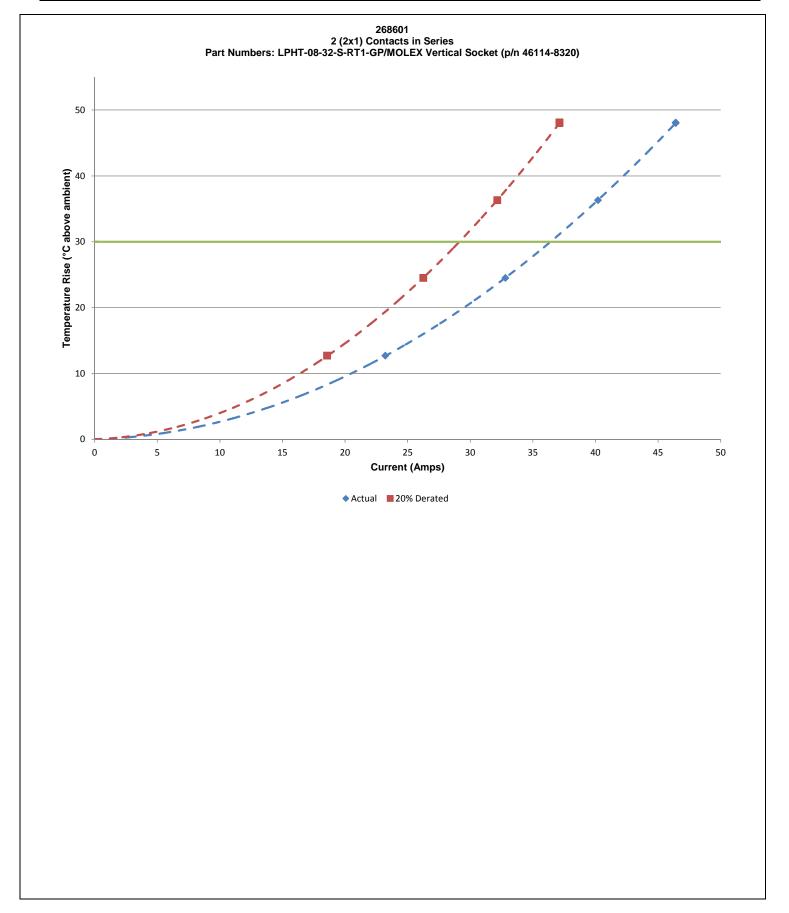
#### **DATA SUMMARIES**

## **TEMPERATURE RISE (Current Carrying Capacity, CCC):**

- 1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.
- 2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.
- 3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less than 1° C (computer controlled data acquisition).
- 4) Adjacent contacts were powered:
  - a. Linear configuration with 2 adjacent conductors/contacts powered

268601 2 (2x1) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)





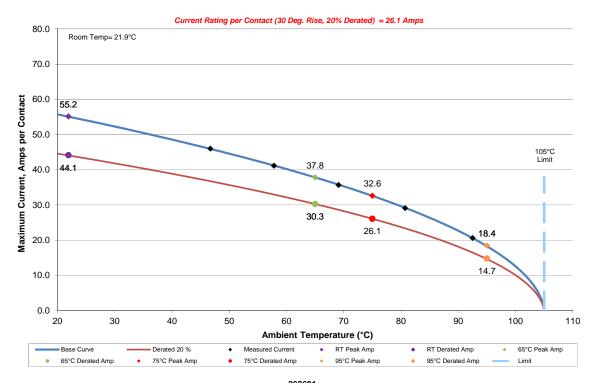
Part description: LPHT/ Molex socket

## **DATA SUMMARIES Continued**

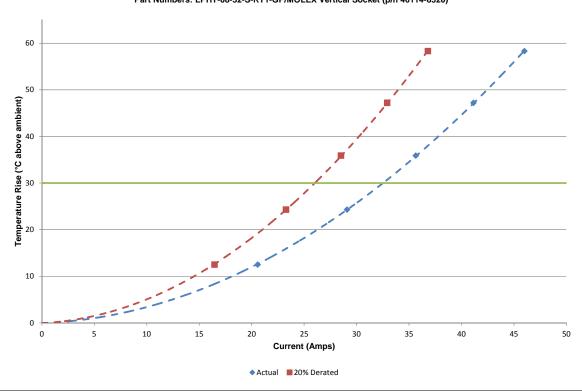
b. Linear configuration with 4 adjacent conductors/contacts powered

Tracking Code: 264949\_Report\_Rev\_1

268601 4 (2x2) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



268601 4 (2x2) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



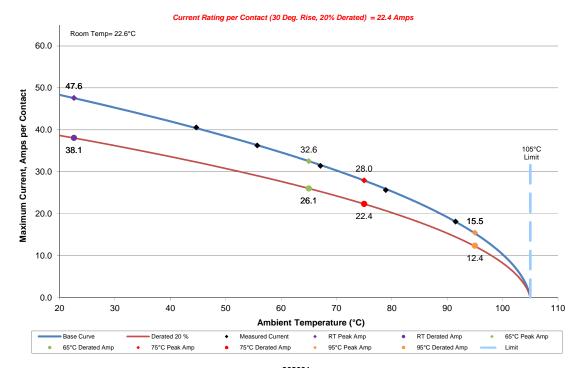
Tracking Code: 264949\_Report\_Rev\_1 Part #: LPHT-08-32-S-RT1-GP/Molex socket: 46114-8320

Part description: LPHT/ Molex socket

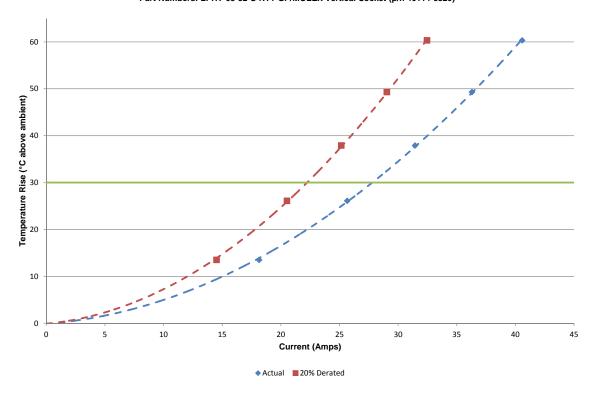


c. Linear configuration with 6 adjacent conductors/contacts powered

268601 6 (2x3) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



268601 6 (2x3) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



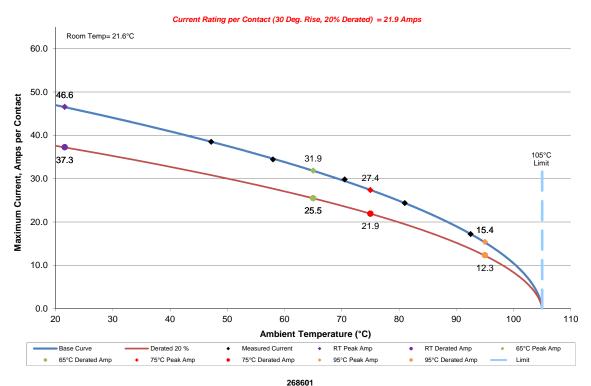
Part description: LPHT/ Molex socket

## **DATA SUMMARIES Continued**

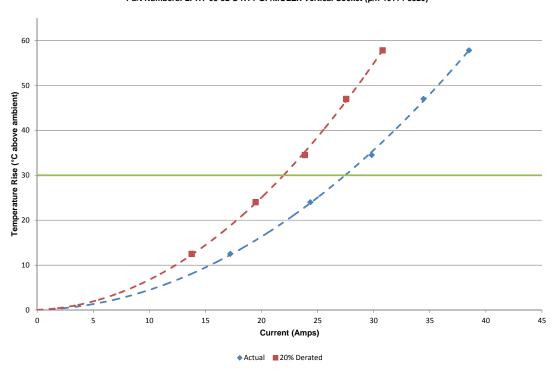
d. Linear configuration with all adjacent conductors/contacts powered

Tracking Code: 264949\_Report\_Rev\_1

268601 8 (All Power) Contacts in Series Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



8 (All Power) Contacts in Series
Part Numbers: LPHT-08-32-S-RT1-GP/MOLEX Vertical Socket (p/n 46114-8320)



Tracking Code: 264949 Report Rev\_1 Part #: LPHT-08
Part description: LPHT/ Molex socket

# **DATA SUMMARIES Continued**

## **MATING-UNMATING FORCE:**

	Initial				After 25 Cycles			
	Mating		Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	44.57	10.02	31.94	7.18	46.84	10.53	37.63	8.46
Maximum	48.13	10.82	37.90	8.52	50.13	11.27	42.43	9.54
Average	45.60	10.25	35.89	8.07	48.25	10.85	40.94	9.20
St Dev	1.27	0.29	1.89	0.43	1.10	0.25	1.67	0.38
Count	8	8	8	8	8	8	8	8
		After 50	Cycles			After 75	Cycles	
	Mat	ing	Unmating		Mat	ing	Unm	ating
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	48.48	10.90	38.21	8.59	49.42	11.11	39.72	8.93
Maximum	51.91	11.67	44.97	10.11	53.29	11.98	46.97	10.56
Average	49.95	11.23	42.51	9.56	51.05	11.48	44.04	9.90
St Dev	1.08	0.24	2.19	0.49	1.16	0.26	2.54	0.57
Count	8	8	8	8	8	8	8	8
		After 100	O Cycles		After Humidity			
	Mat	ing	Unm	ating	Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	50.35	11.32	41.37	9.30	36.16	8.13	26.69	6.00
Maximum	54.09	12.16	48.39	10.88	42.97	9.66	32.60	7.33
Average	51.93	11.68	45.62	10.26	40.14	9.03	30.32	6.82
St Dev	1.12	0.25	2.80	0.63	2.08	0.47	2.20	0.50
Count	8	8	8	8	8	8	8	8

Part description: LPHT/ Molex socket

### **DATA SUMMARIES Continued**

## **LLCR Mating/Unmating Durability Group**

Tracking Code: 264949 Report Rev 1

- 1). A total of 192 points were measured.
- 2). EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3). A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4). The following guidelines are used to categorize the changes in LLCR as a result from stressing.
  - a. <= +5.0 mOhms: -----Stable
  - b. +5.1 to +10.0 mOhms:------Minor
  - c. +10.1 to +15.0 mOhms:------Acceptable
  - d. +15.1 to +50.0 mOhms:------Marginal
  - e. +50.1 to +2000 mOhms------Unstable
  - f. > +2000 mOhms: ------Open Failure

	LLCR	Measurement S	Summaries by Pin	Туре	
Date	6/29/2013	6/29/2013 7/4/2013		7/26/2013	
Room Temp (Deg C)	23	24	23	25	
Rel Humidity (%)	57	56	56	59	
Technician	Kason He	Kason He	Kason He	Kason He	
mOhm values	Actual	Delta	Delta	Delta	
	Initial	100 Cycles	Therm Shck	Humidity	
		Pin Type	1: Signal		
Average	18.59	0.33	0.40	0.43	
St. Dev.	2.11	0.37	0.35	0.45	
Min	12.65	0.01	0.00	0.01	
Max	22.83	3.32	2.15	3.39	
Summary Count	160	160	160	160	
Total Count	160	160	160	160	
		Pin Type	2: Power		
Average	1.21	0.04	0.05	0.04	
St. Dev.	0.27	0.10	0.11	0.04	
Min	0.87	0.00	0.00	0.00	
Max	1.69	0.59	0.67	0.13	
Summary Count	32	32	32	32	
Total Count	32	32	32	32	

LLCR Delta Count by Category						
	Stable Minor Acceptable Marginal Unstable Op					Open
mOhms	<b>&lt;=</b> 5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
100 Cycles	192	0	0	0	0	0
Therm Shck	192	0	0	0	0	0
Humidity	192	0	0	0	0	0

Tracking Code: 264949\_Report\_Rev\_1

Part description: LPHT/ Molex socket

## **EQUIPMENT AND CALIBRATION SCHEDULES**

**Equipment #:** HZ-TCT-01

**Description:** Normal force analyzer **Manufacturer:** Mecmesin Multitester **Model:** Mecmesin Multitester 2.5-i

**Serial #:** 08-1049-04

**Accuracy:** Last Cal: 4/26/2013, Next Cal: 4/25/2014

**Equipment #:** HZ-THC-01

**Description:** Humidity transmitter

**Manufacturer:** Thermtron

**Model:** SM-8-8200 **Serial #:** 38846

**Accuracy:** Last Cal: 2/28/2013, Next Cal: 2/27/2014

**Equipment #:** HZ-MO-05 **Description:** Micro-ohmmeter **Manufacturer:** Keithley

**Model:** 3706 **Serial #:** 1285188

**Accuracy:** Last Cal: 11/15/2012, Next Cal: 11/14/2013

**Equipment #:** HZ-TSC-01

**Description:** Vertical Thermal Shock Chamber

Manufacturer: Cincinnatti Sub Zero

Model: VTS-3-6-6-SC/AC Serial #: 10-VT14994 Accuracy: See Manual

... Last Cal: 06/27/2013, Next Cal: 06/26/2014

**Equipment #:** MO-09

**Description:** Model 2750 Multimeter/Switch System (Integra Series)

Manufacturer: Keithley

**Model: 2750** 

**Serial #:** WDC-874817

**Accuracy:** Last Cal: 11/15/2012, Next Cal: 11/14/2013

**Equipment #: PS-09** 

**Description:** 60 V, 50 A DC Power Supply - AutoRanging SO

Manufacturer: Hewlett Packard / Agilent

**Model:** AT-6032A **Serial #:** US38322853

**Accuracy:** Last Cal: 11/15/2012, Next Cal: 11/14/2013